# ISPD 2014 Detailed Routing-Driven Placement Contest Benchmark Design Suite A

www.ispd.cc/contests/14/ispd2014\_contest.html

#### **Outline**

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- 4. DEF Placement Requirements & Evaluation Metrics
- 5. DEF Placement Submission Procedure
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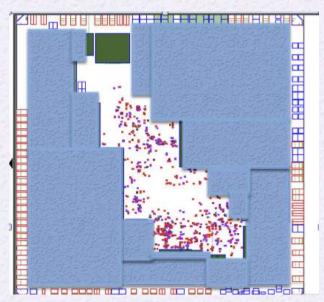
# 1. Motivation

#### **Motivation**

- Increasing complexity of design rules
  - miscorrelation between global routing and detailed routing
  - traditional placement approaches rendered inadequate
- Example routability challenges for placement
  - Netlist: high-fanout nets, data paths, timing objectives
  - Floorplan: placement utilization, irregular placeable area, thin channels between blocks
  - Routing constraints: blockages and restrictions by layer
  - Design rules: min-spacing, pin geometry, edge-type, end-of-line, ...

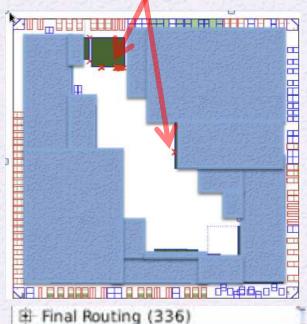
#### Global/Detail Routing Miscorrelation Example

#### **GR** congestion map



	Х	Υ	Via	Total	
Edge Count	1267068	1267137	2115090	4649295	
Overflow Edges	6	0	0	6	
Overflow as %	0.000129052	0	Θ	0.000129052	
Worst	2	1	0.761905	2	
Average	0.200374	0.259198	0.0434537	0.108448	
Overflow Nodes	1184	48	-1	1232	
Wire Length	1.24525e+11	1.21068e+11	3.85303e+06	2.45593e+11	



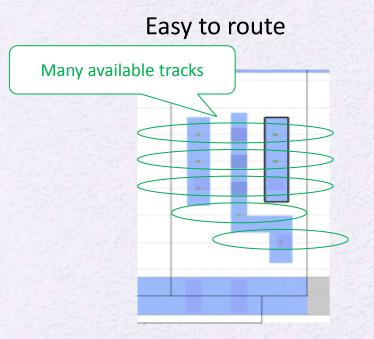


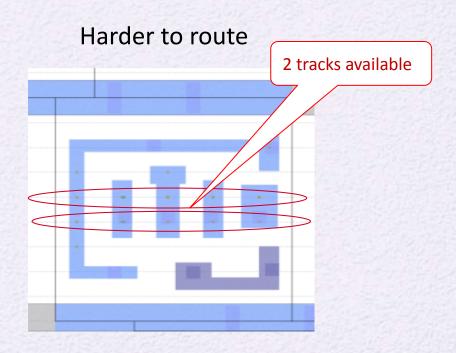
- DRC (166) H- short (137)
  - min hole (1)
  - min diff space (5)
  - ⊕-cut size (21)
  - ① cut min space (1)
  - ⊕-cut number (1)

# **Pin Geometry Challenges**

#### Dense metal1 pins:

- Complex DRC rules: cut space, minimum metal area, end-of-line rules, double patterning rules, etc.
- Challenging to pre-calculate routable combinations





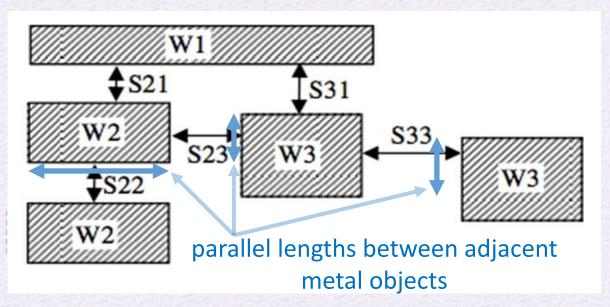
# 2. Sample Design Rules

## **Introduction to Design Rules**

- For 65nm technology and below, many rules are imposed to ensure a printable GDSII mask.
- The examples provided here are not comprehensive.
   They are common on the benchmarks for this contest.
- For the LEF/DEF format specification of design rules, see www.si2.org/openeda.si2.org/projects/lefdef.

## **Minimum Spacing Rule**

- There is a required minimum spacing between any two metal edges.
- The minimum spacing requirement depends on:
  - 1. The widths of the two adjacent metal objects.
  - 2. The parallel length between the two adjacent metal objects.

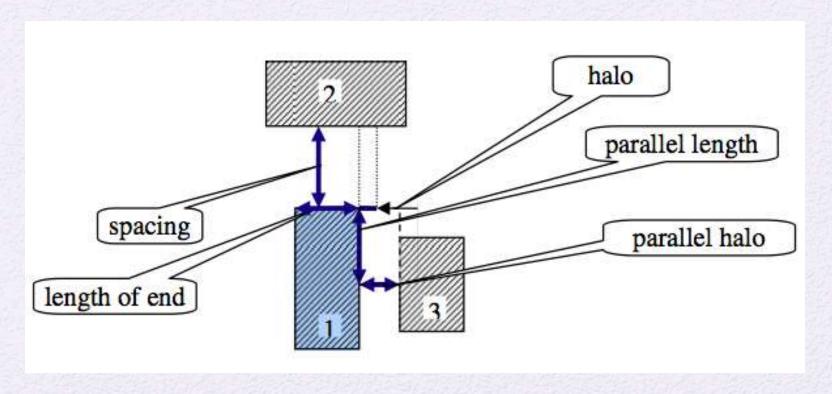


#### **End of Line Rule**

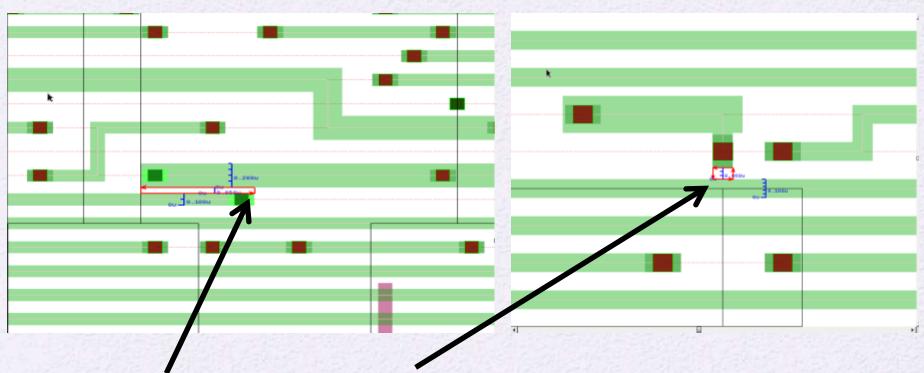
- EOL is a spacing rule between two objects. However, more than two shapes can be involved, and various distance metrics can be used.
- A 3-object EOL between the top of object 1 and the bottom of object 2 is illustrated on the next slide.
- EOL is a function of these four parameters:
  - Length of end: A minimum width for object 1 to avoid a violation.
  - Parallel length: Vertical distance below the top of object 1 within which object 3 will increase the minimum spacing between objects 1 and 2.
  - Halo: Area around corner of object 1 where object 2 may trigger EOL rule.
  - Parallel halo: Min spacing between object 1 and object 3 to avoid a violation.
    - The parallel halo is an extra spacing requirement in addition to the EOL spacing.

#### **End of Line Parameters**

EOL spacing applied to objects 1 and 2. Because object 3 overlaps the parallel length from the top of edge 1, EOL spacing between objects 1 and 2 will be required. Object 3 must remain outside the parallel halo.



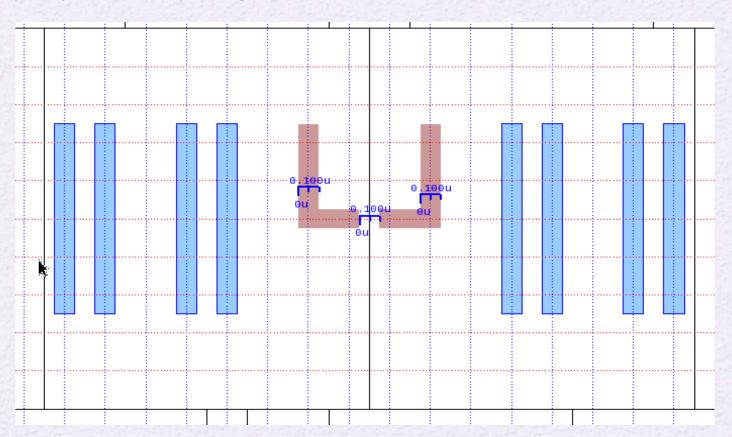
# Min Spacing and End-Of-Line Spacing Violation Examples



Example **minimum spacing** and **EOL spacing** violations between routing objects within over-congested areas. Most of these violations occur in the vicinity of pins assigned with the EM\_NDR non-default routing rule.

# **End-Of-Line Spacing Violation Example**

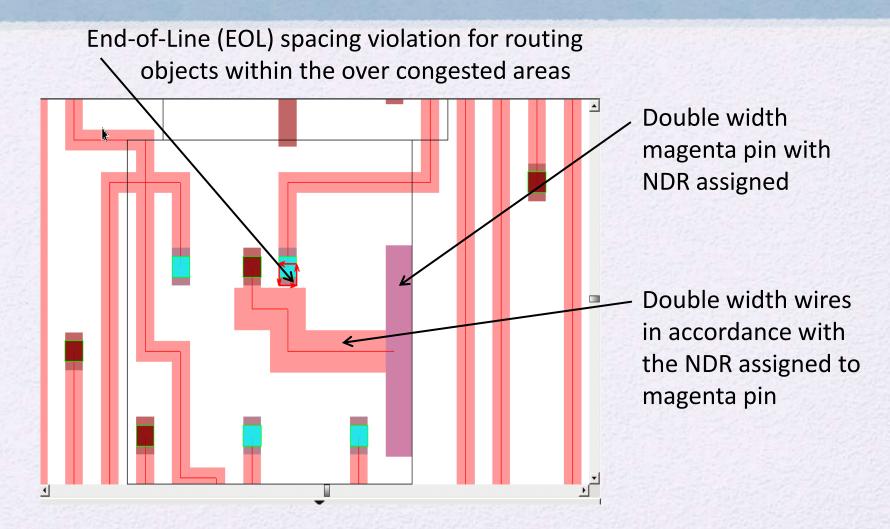
L-shaped pin – EOL spacing violations can occur if two such cells are abutted.



# Non-Default Routing Rule (NDR)

- Non-default routing rules may specify:
  - Increased wire spacing for a net
  - Increased wire width for a net
  - Increased via cut number at selected junctions
     Cut # = number of vias connected to a wire at a single junction
- NDR may be assigned to a cell pin for wires or vias connecting to it
- NDR may or may not accompany increased pin width or specific non-rectangular pins
- NDRs are specified in the floorplan DEF file but may be assigned to a pin in the cell LEF file

# **Example End-of-Line Spacing Violation Due to an NDR**



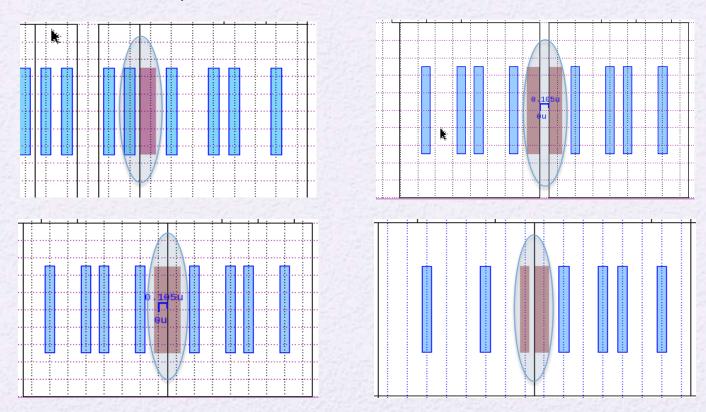
## **Edge-Type Rule**

- Each vertical edge of a cell may have specified minimum spacings from any other vertical cell edge that can be placed right or left of it.
- They may be for yield, different implant dosages, pin reachability, etc.
- Examples:
  - The **left** edge of every ao22s01 cell must be placed at least 0.400um away from the **left** edge of every other ao22s01 cell.
  - The **left** edge of every ao22s01 cell must be placed at least 0.800um away from the **right** edge of every other a022s01 cell adjacent to it.

# **Edge-Type Spacing Violation Examples**

Double width metal2 is used for the red pins.

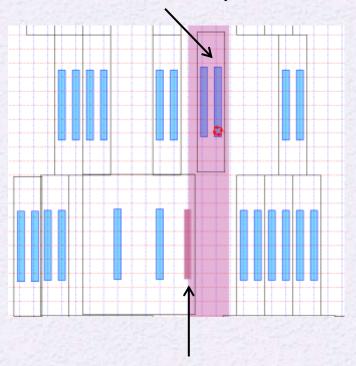
An **edge-type** double spacing constraint is also enforced at the adjacent cell edge. Below are four examples of violations of this:



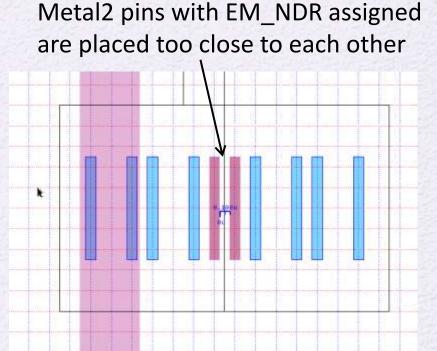
## **Blocked Pin Access Violation Examples**

A blocked pin cannot be reached by a via or wire without violations.

Metal1 pins under metal2 stripe are not accessible by via1 vias



Metal2 pin overlaps metal2 stripe



# 3. Benchmark Suite A

#### **Benchmark Source**

- This benchmark suite is adapted from the ISPD 2013 gate sizing contest.
- The rectangular floorplans have no fixed or movable macros.
- Please note that we will release a second suite on January 10<sup>th</sup>
  adapted from the DAC 2012 routability-driven placement contest
  that has more complex floorplans with fixed macros.

#### **Data Format**

#### Each benchmark has four files:

- **tech.lef** (technology LEF): Physical characteristics of the routing layers, vias, placement site types, etc.
- **cells.lef** (physical LEF): Physical characteristics of the technology library for the standard cell library, macros, and I/O cells, etc.
- **floorplan.def**: Design-specific logical and physical information that represent the design during various stages of the physical design flow. This includes netlist connectivity, grouping information, physical constraints, cell locations and orientations, routing geometry data, etc.
- design.v: A gate-level Verilog netlist for the design.

Library Exchange Format (LEF) and Design Exchange format (DEF) 5.7 are detailed here: <a href="www.si2.org/openeda.si2.org/projects/lefdef">www.si2.org/openeda.si2.org/projects/lefdef</a>

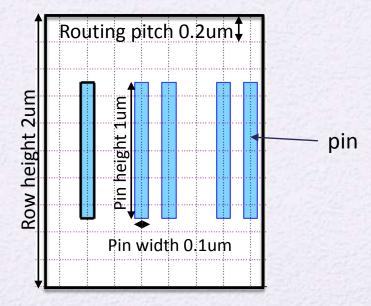
# **Metal Routing Layers**

- There are 5 routing layers, but only 4 routing layers are available: metal2, metal3, metal4, and metal5.
- Metal1 may only be used for vias to metal1 pins.
   Metal1 is otherwise excluded from routing.
- On some designs, metal5 is also blocked to increase routing difficulty.
  - This is representative of designs where fewer routing layers are used to reduce fabrication cost.
- More conservative design rules have been added: min spacing, edge type, end-of-line, etc.
- Non-default routing rules (double width, double spacing, double cut, vias, layer restrictions) are assigned to medium fanout nets and to some cell pins.

# **Standard Cell Library**

- Based on 65nm technology.
- The routing pitch (minimum track height) is 0.2um.
- There are 10 routing tracks per standard cell row (i.e. 2.0um tall).
- All movable cells are downsized to their minimum area.
- All movable cells are single-row high.

Example standard cell:

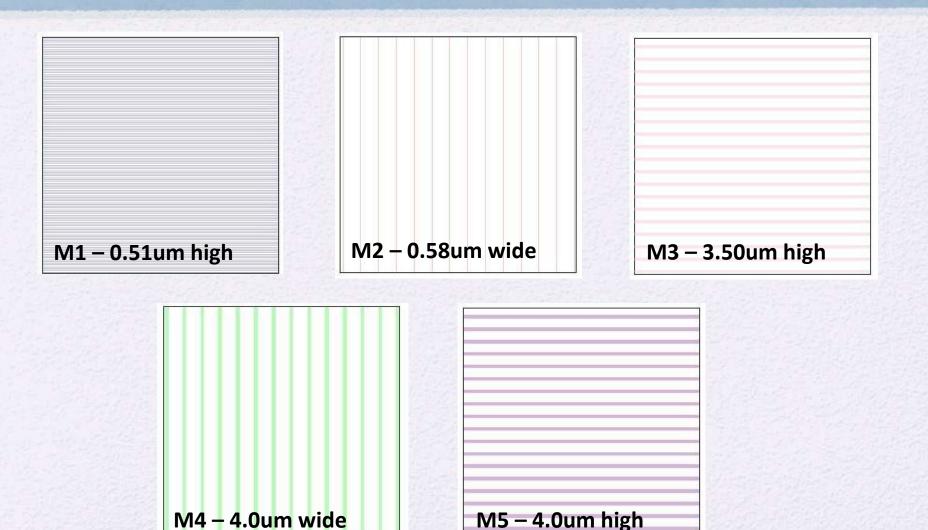


# Power/Ground (PG) Mesh

- A dense PG mesh has been inserted.
- Each routing layer has uniformly spaced PG rails parallel to its preferred routing direction.
- Rail thickness is constant on each layer but varies by layer.
- PG routing-track utilization varies across layers and test cases.
  - Example edit\_dist test case (placement utilization: 43%)

Metal layer	M1	M2	M3	M4	M5
PG routing track utilization	0%	6%	27%	24%	30%

# Power/Ground (PG) Mesh



M5 – 4.0um high

# Spacing Rules Example in Technology LEF

```
LAYER metal2
 TYPE
                  ROUTING ;
 DIRECTION
                  VERTICAL ;
 PITCH
                  0.200;
                  0.100 ;
 OFFSET
                  0.1;
 WIDTH
 MAXWIDTH
                  10.0 ;
 SPACINGTABLE
                  0.00 0.40 0.46
                                      1.40
                                             4.10
 PARALLELRUNLENGTH
       0.00
                 0.10 0.10 0.10 0.10 0.10
 WIDTH
                 0.10 0.12 0.12 0.12 0.12
 WIDTH 0.30
      0.46
                 0.10 0.12 0.15 0.15 0.15
 WIDTH
      1.40 0.10 0.12 0.15 0.52 0.52
 WIDTH
        4.10 0.10
                         0.12
                                0.15 0.52
                                             1.40 ;
 WIDTH
 PROPERTY LEF57 SPACING "SPACING 0.12 ENDOFLINE 0.14 WITHIN 0.045
PARALLELEDGE 0.12 WITHIN 0.12;";
```

# Edge-Type Rules Example in Technology LEF

```
PROPERTYDEFINITIONS
  LAYER LEF57 SPACING STRING ;
  LAYER LEF57 MINSTEP STRING ;
 MACRO LEF58 EDGETYPE STRING ;
  LIBRARY LEF58 CELLEDGESPACINGTABLE STRING
  "CELLEDGESPACINGTABLE
   EDGETYPE 1 2 0.400
    EDGETYPE 1 1 0.400
   EDGETYPE 2 2 0.000;";
END PROPERTYDEFINITIONS
```

# Min-Step, Area, Minimum Cut Rules in Technology LEF

```
PROPERTY LEF57_MINSTEP "MINSTEP 0.1 MAXEDGES 1;";
AREA 0.051;
MINIMUMCUT 2 WIDTH 0.400;
MINIMUMCUT 4 WIDTH 0.720;
MINIMUMCUT 2 WIDTH 0.400 LENGTH 0.400 WITHIN 0.820;
MINIMUMCUT 2 WIDTH 2.100 LENGTH 2.100 WITHIN 2.100;
MINIMUMCUT 2 WIDTH 3.200 LENGTH 8.000 WITHIN 5.200;
```

# Common Design Rules in in All Physical LEF Data

- 1. Most cell pins are located on metal1 layer, and are 0.5 pitches wide and 5 pitches high.
- 2. NDR with double wire width and double wire spacing assigned to all nets with fanout > 10.
- 3. Standard cell ms00f80: driving pin is promoted to metal2 layer to check ability of placement to prevent intersection with PG rails.
- 4. Standard cell ao22s01: output pin near edge on metal1, but has edge-type constraint with 2x spacing (0.2um).

# Design Rules Variants in Physical LEF Data

5. Standard cell oa22f01: Promoted output pin "o" to metal2 and imposed 2x width, 2x spacing, 2-cut vias EM\_NDR.

This restriction should be observed within 1.0 um (i.e. 5 pitches) of the output pin, afterwards it is switched to the default rule.

There are two variants of this rule:

- Double width (0.2um) for pin "o" and edge-type spacing 0.2um assigned to edge next to pin "o", with EM\_NDR double wire width and double wire spacing.
- II. Single-width L-shaped pin for "o".

## **Physical LEF Data Scenarios**

Based upon the design rules variants mentioned in the previous slide, there are three scenarios of physical LEF data provided in this benchmark:

- Scenario 1: cell.lef contains rules 1-4.
- Scenario 2: cell.lef contains rules 1-4 and rule 5.I.
- Scenario 3: cell.lef contains rules 1-4 and rule 5.II.

# The Design Suite

- The design suite contains 8 designs adapted from the ISPD 2013 gate-sizing contest:
  - mgc\_des\_perf\_1
  - mgc\_des\_perf\_2
  - mgc\_edit\_dist\_1
  - mgc\_edit\_dist\_2

- mgc\_fft
- mgc\_matrix\_mult
- mgc\_pci\_bridge32\_1
- mgc\_pci\_bridge32\_2
- Each test case is comprised of four files:

cells.lef, design.v, floorplan.def, and tech.lef.

# 4. DEF Placement Requirements & Evaluation Metrics

# Submitted DEF Placement Requirements

- You are expected to provide a DEF file containing the output of your placer.
- Placement legalization is recommended but not required.
- The file name must be gzipped and prepended with the design name (e.g. mgc\_fft.def.gz).
- Please modify the COMPONENTS section of the provided floorplan.def file to place all UNPLACED cells with appropriate placement locations from your placer.
  - Add the bottom left coordinate (BLC) of each placed cell and change
  - "+ UNPLACED" tag to "+ PLACED ( <x\_BLC> <y\_BLC> ) <cell orientation>"
  - Example: u1 INVX1 + PLACED ( 60000 20000 ) N ;
- Changes other than to the COMPONENTS disqualify the submitted placement.

#### **Evaluation Metric**

- Submitted DEF placement solutions will be evaluated by the quality of their detailed routes in Mentor Graphics' Olympus-SoC<sup>TM</sup> place and route tool.
- A placement checker will check the validity of placed designs. If the submitted DEF placement is invalid, you will receive an e-mail with the respective errors.
- Valid placements will be legalized, routed, and scored based on cell legalization perturbations, detail routed wire length, routing violations, and design-rule check (DRC) violations.
- Note 1: Even though it is not part of the incremental evaluations, run time
   will be part of the final evaluation metric.
- **Note 2**: Excessive memory usage will be penalized. Memory limits for this suite will be posted later.
- Note 3: The contest organizers may change these metrics if necessary for a fair evaluation.

# **DEF Placement Validity Checker**

- A Perl script shall check that the submitted DEF placement meets the following minimum requirements:
  - All cells must be placed within the floorplan boundary
  - No cells may be added, removed, or changed
  - Locations of fixed cells and I/O pins must not change
  - Floorplan boundary must not change
  - Net connections must not change
    - Connectivity can be omitted from the placed DEF
- Placed DEF files that have any of these problems will not be evaluated.
- A summary of these errors will be emailed to the contestant.
   The script is provided to contestants to check before submission.

# **Placement Legalization**

Placement legalization will fix the following issues in submitted design.def files:

- Overlaps between cells or with blockages, and edge-type violations
- Cells not aligned on the standard cell rows
- Cells with incorrect orientation
- Cell pins that short to the PG mesh
- Blocked cell pins that are inaccessible due to the PG mesh
- DRC placement violations between standard cells

Significant cell displacement in legalization is penalized (per  $S_{DP}$  score), so we recommend minimizing such issues in your submission.

# Final Placement Score $S = S_{DP} + S_{DR} + S_{WL} + S_{CPU}$

- Each of the following quantities contributes to the total score:
  - DP: average legalization displacement of the 10% most displaced of all cells
  - DR: number of detailed-routing violations
  - WL : routed wirelength
  - CPU: total runtime of global placement, legalization, and routing
- A lower score is better.
- Placements for which  $DP \ge 25.25$  or  $CPU \ge CPU_{max}$  are invalid, receiving the maximum score of S = 100.
- Each category score except *DP* is normalized by the median unscaled score taken over all contestants' placements for the given benchmark.
- Each normalized category score is scaled to the interval [0, 25].
  - Affine scaling  $f_{aff}$ :  $[a,b] \rightarrow [0, 25]$  is used for all categories except DR:  $f_{aff}(t) = 25(t-a)/(b-a)$ , where  $a \le t \le b$ .
  - Quadratic scaling is used for DR, as described below.

#### Legalization Displacement Score S<sub>DP</sub>

- The raw quantity DP is the average Manhattan displacement of the 10% most displaced of all cells.
- Score  $S_{DP}$  is defined as follows.
  - $S_{DP} = 0$  if  $DP \le 0.25$  std-cell row heights
  - $S_{DP} = 25$  if  $DP \ge 25.25$  std-cell row heights
  - Otherwise,  $S_{DP} = DP 0.25$
- In all cases,  $0 \le S_{DP} \le 25$ .
- If  $S_{DP}$  == 25, then detailed routing will be skipped, and  $S_{WL}$  = 25,  $S_{DR}$  = 25, and  $S_{CPU}$  = 25. Placement is invalid.

#### Detailed routing score $S_{DR}$

- Weighted sum  $DR = DR(p) = w_1v_1 + w_2v_2 + w_3v_3 + w_4v_4$  is computed from the number of violations  $v_i$  of routing violation type i and weight  $w_i$  in the table below.
- Let  $DR_{med}$  denote the median of these unscaled sums DR over valid placements p.
- If  $DR/(1+DR_{med}) > 100$ , then  $S_{DR} = 25$ .
- Otherwise,  $S_{DR} = 2.5 (DR/(1+DR_{med}))^{1/2}$ . In all cases,  $0 \le S_{DR} \le 25$ .

Square root is taken, as there may be a wide range in violation counts.

Design Violation Type	Weighting w <sub>i</sub>
Routing open	1.0
Routing blocked pin	1.0
Routing short	1.0
Design rule check (DRC) violation	0.2

#### Detail-Routed Wirelength Score S<sub>WL</sub>

- Unscaled score WL is simply the final detail-routed wirelength reported by the router.
- Over all valid placements p on a benchmark with  $S_{DP}(p) < 25$ , let
  - $WL_{med}$  = the median of the WL(p).
  - $WL_{min}$  = the minimum of the WL(p).
- If  $WL \ge 5 \times WL_{med}$ , then  $S_{WL} = 25$ .
- Otherwise,  $S_{WL} = f_{aff}(WL / WL_{med})$ , where  $f_{aff}$  denotes affine scaling from  $[WL_{min} / WL_{med}]$ , 5] into [0, 25].

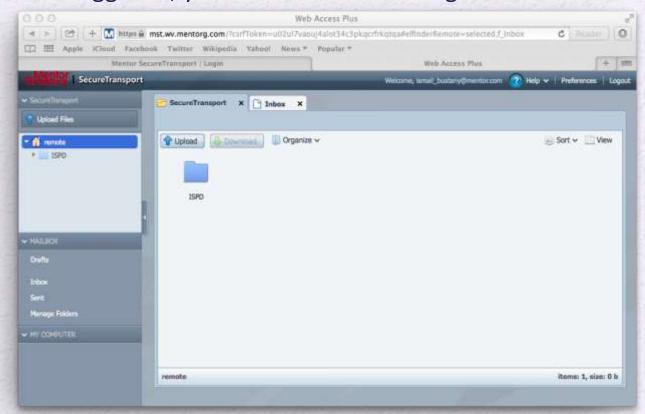
#### Run-time Score S<sub>CPU</sub>

- Let CPU = total wall-clock time for placement, legalization, global and detailed routing on one benchmark, on an unloaded machine with 8 cores.
- Each benchmark suite has a hard run-time limit per test case,  $CPU_{max}$ .
  - Benchmark Suite A: CPU<sub>max</sub> = 24 hrs per test case
- If  $CPU > CPU_{max}$ , then  $S_{CPU} = 25$ ,  $S_{DP} = 25$ ,  $S_{DR} = 25$ ,  $S_{WL} = 25$ , and S = 100.
- Over all valid placements p on the benchmark with  $CPU(p) < CPU_{max}$ , let  $CPU_{min}$  = minimum of the CPU(p) and  $CPU_{med}$  = median of the CPU(p).
- $S_{CPU} = f_{aff}(CPU / CPU_{med})$ , where  $f_{aff}$  denotes affine scaling from  $[CPU_{min} / CPU_{med}, CPU_{max} / CPU_{med}]$  into [0, 25].

- Please visit https://mst.mentorg.com/
- Login using your support-net account email and password. If you do not have a support-net account, please e-mail ispd2014contest@gmail.com.

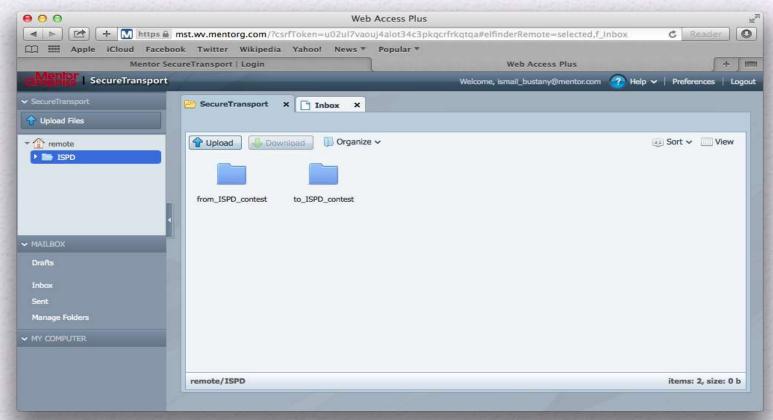


3. Once logged in, you will see the following screen:



4. Click open the ISPD folder.

5. You will see two folders: **from\_ISPD\_contest** and **to\_ISPD\_contest**:



Upload your DEF placement to the to\_ISPD\_contest folder. Please use the design name appended by .def.gz (e.g. mgc\_fft.def.gz). Gzip compressed files are required.

- 7. Your gzipped DEF placement file will be processed. You will be notified by e-mail once the evaluation result is ready to view.
- 8. If the placement file is invalid an error log will be copied to the from\_ISPD\_contest folder; otherwise, a tar gzipped output file will be copied there.
- Upon e-mail notification, please log in to mst.wv.mentorg.com.
   You can download a gzipped tar output file in the from\_ISPD\_contest folder.

**Note:** There will be a limit on the number of submissions per day. Currently, it is 8 submissions per day. This may be adjusted depending on the server load. Updates will be posted on the contest website.

# 6. Contacts

#### **Contact Information**

 Please e-mail any benchmark-related questions to ispd2014contest@gmail.com

### **Contest Organizers**

#### **Mentor Graphics Corporation**

- Ismail Bustany contest chair
- Vladimir Yutsis
- David Chinnery
- Joseph Shinnerl
- John Jones
- Igor Gambarin
- Clive Ellis

#### **National Tsing Hua University**

Wen-Hao Liu

# 7. Acknowledgements

# Acknowledgements

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- Mustafa Ozdal
- Cliff Sze
- Prashant Varshney
- Natarajan Viswanathan
- Alexander Volkov
- Benny Winefeld
- Evangeline Young

<sup>\*</sup>in alphabetical order.

# 8. References

#### References

- M. M. Ozdal, C. Amin, A. Ayupov, S. Burns, G. Wilke, C. Zhuo, "An Improved Benchmark Suite for the ISPD-2013 Discrete Cell Sizing Contest", Proc. of ACM International Symposium on Physical Design, pp. 168-170, 2013.
- 2. Si2, Lef/Def Exchange Format Ver 5.3 to 5.7, 2013. www.si2.org/openeda.si2.org/projects/lefdef